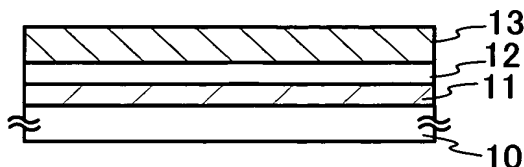


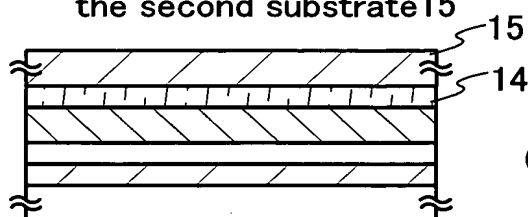
Fig.1

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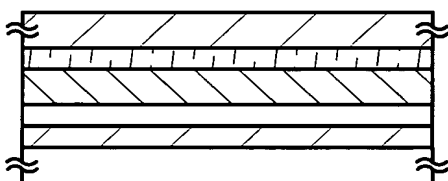
(A) After forming the layer to be peeled



(B) The state after bonding the second substrate 15

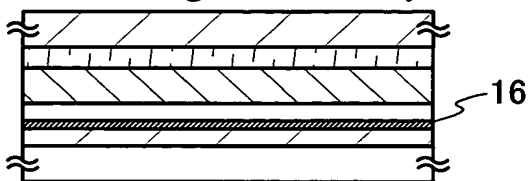


(C) The step of oxidizing the metal layer 11

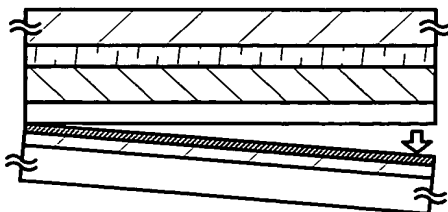


↑ light irradiation

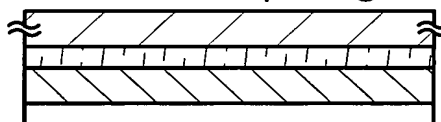
(D) The state after the step of oxidizing the metal layer 11



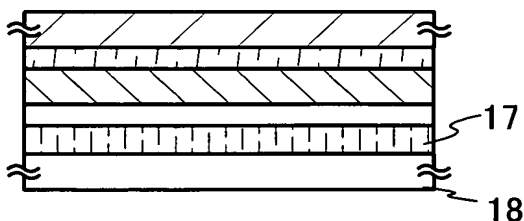
(E) The step of peeling the first substrate 10



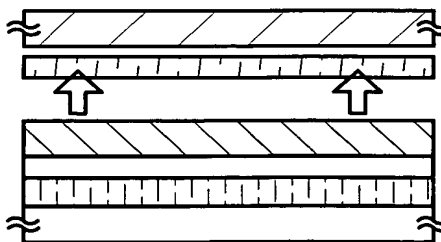
(F) The state after peeling



(G) The state after bonding the third substrate 18



(H) The step of peeling the second substrate



(I) The steps of forming the EL layer and bonding the fourth substrate

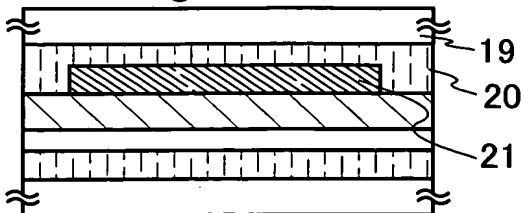


Fig.2

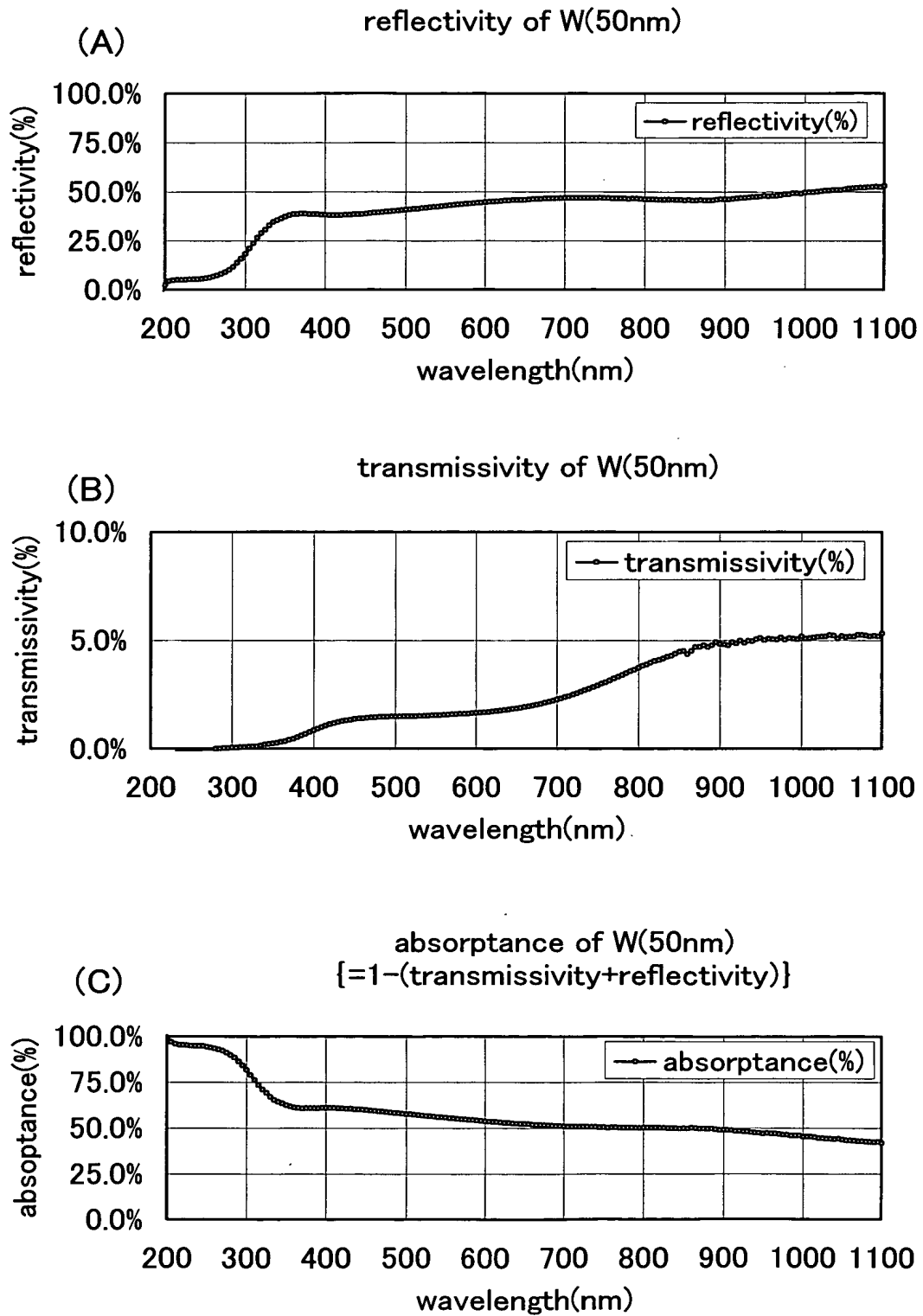


Fig.3

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(A) Forming the semiconductor layer / Forming the insulating film /  
Forming the first conductive film and the second conductive film

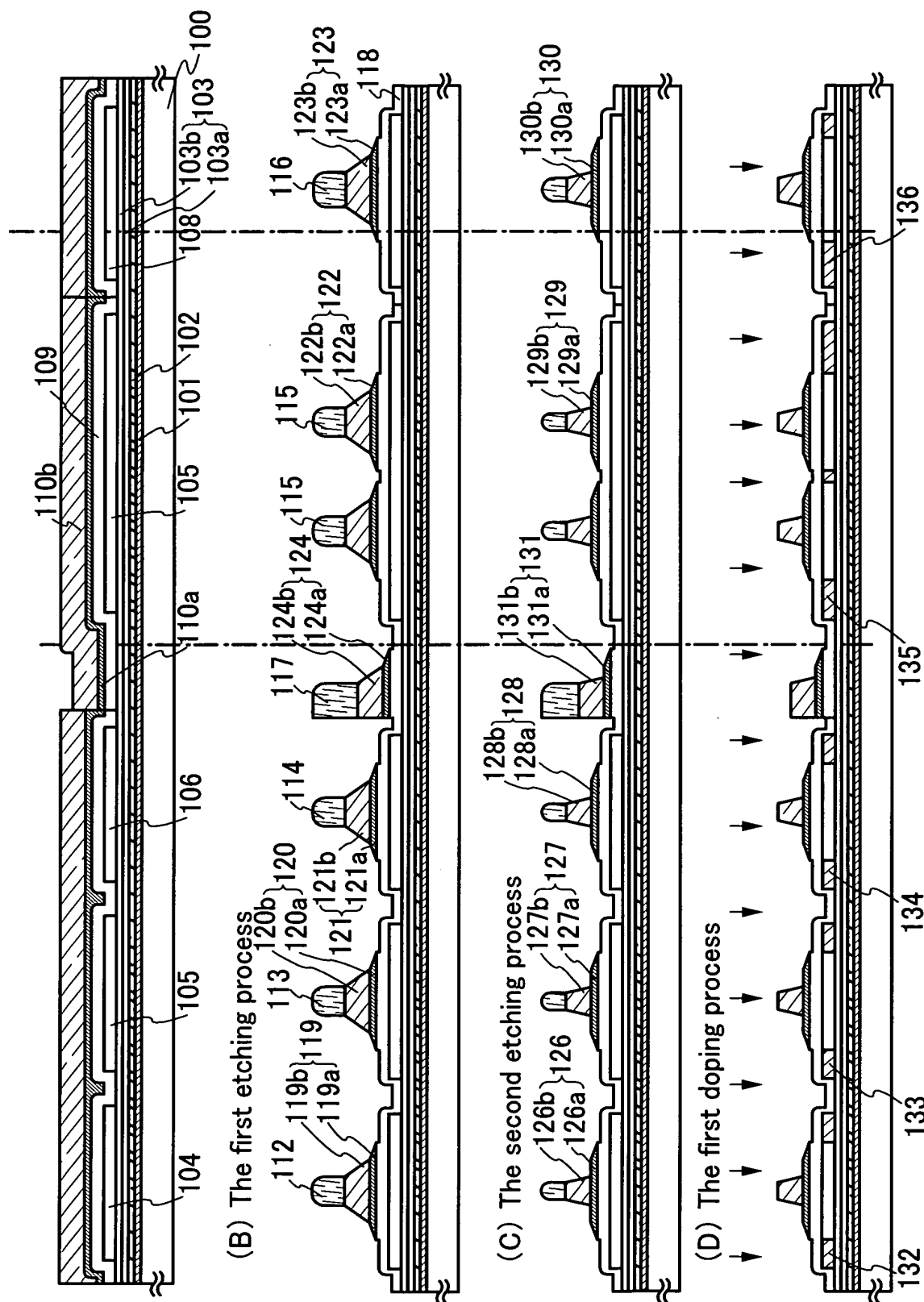


Fig.4

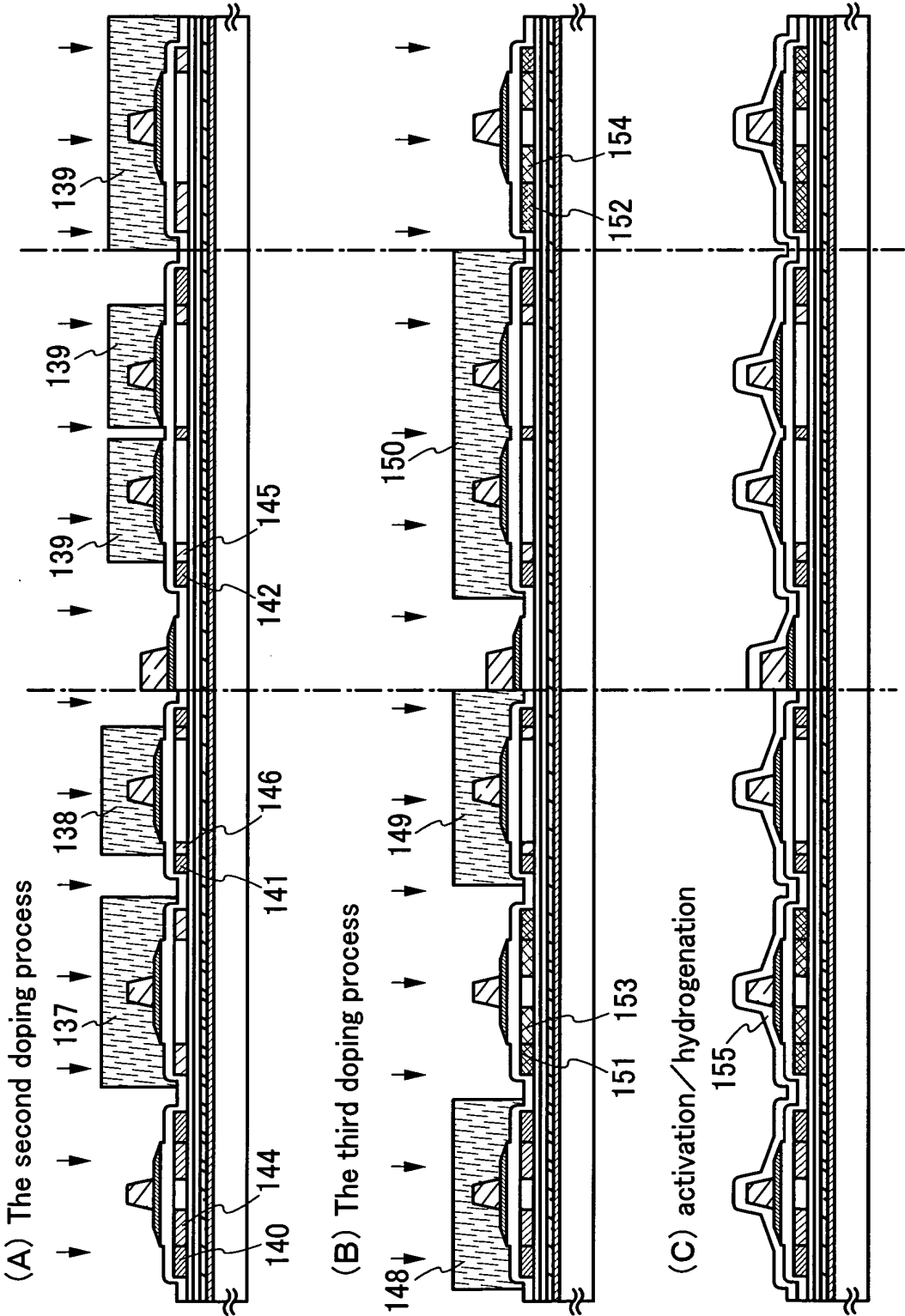


Fig.5

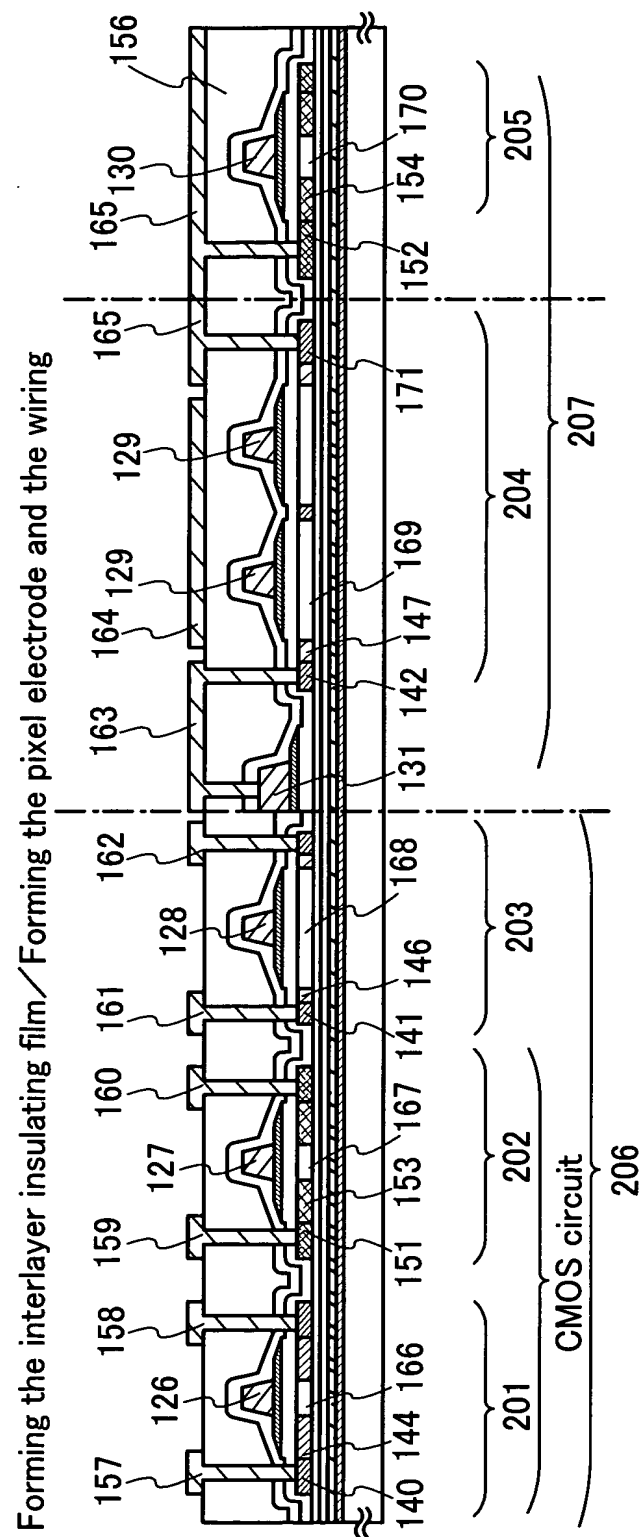


Fig.6

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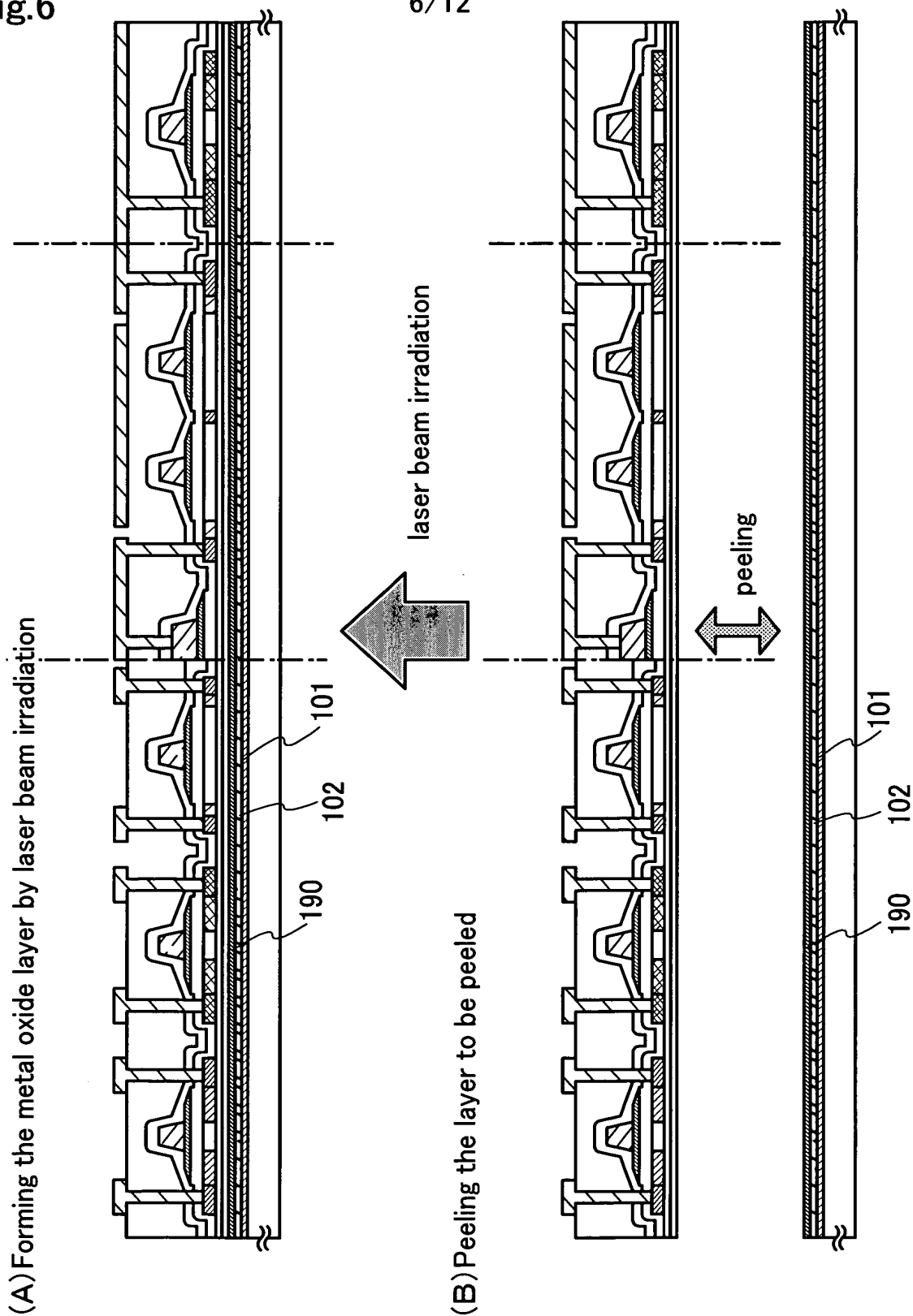


Fig.7

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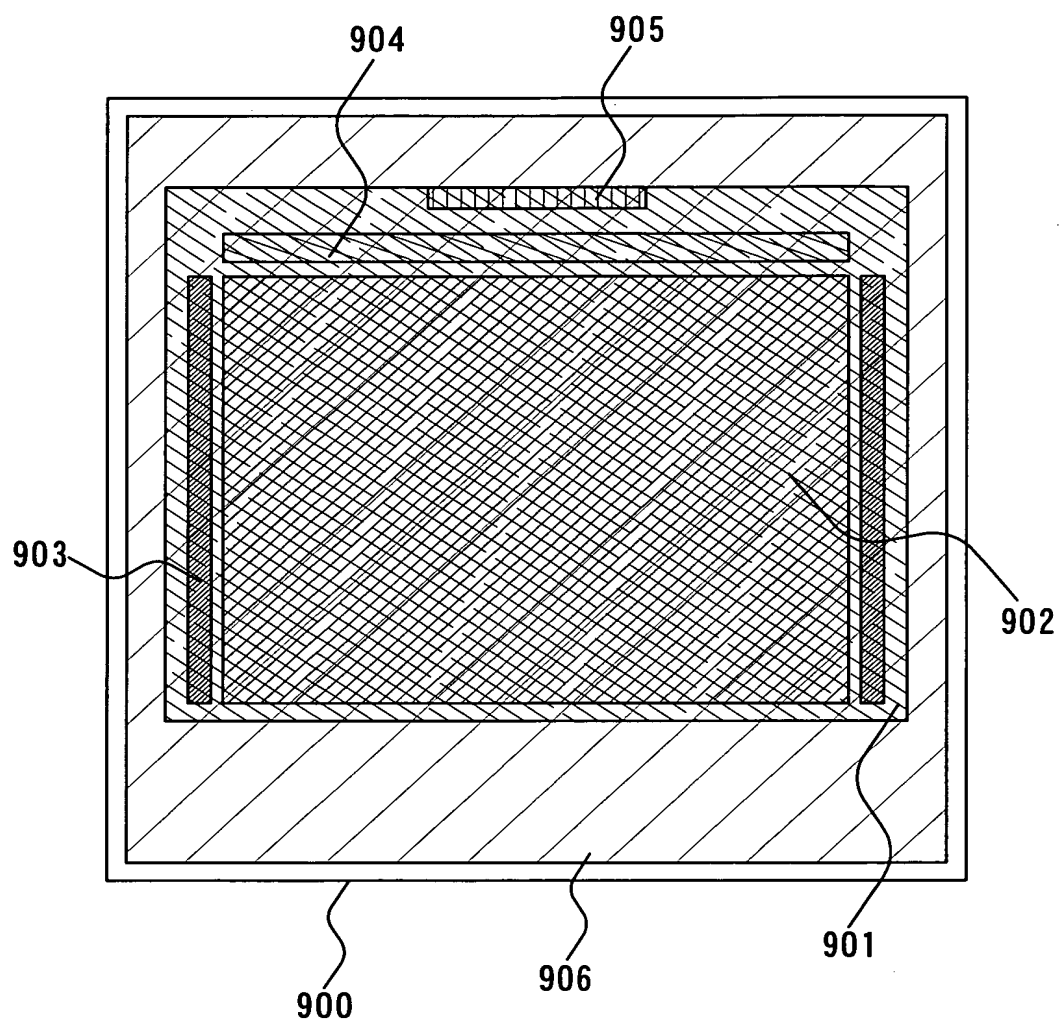


Fig.8

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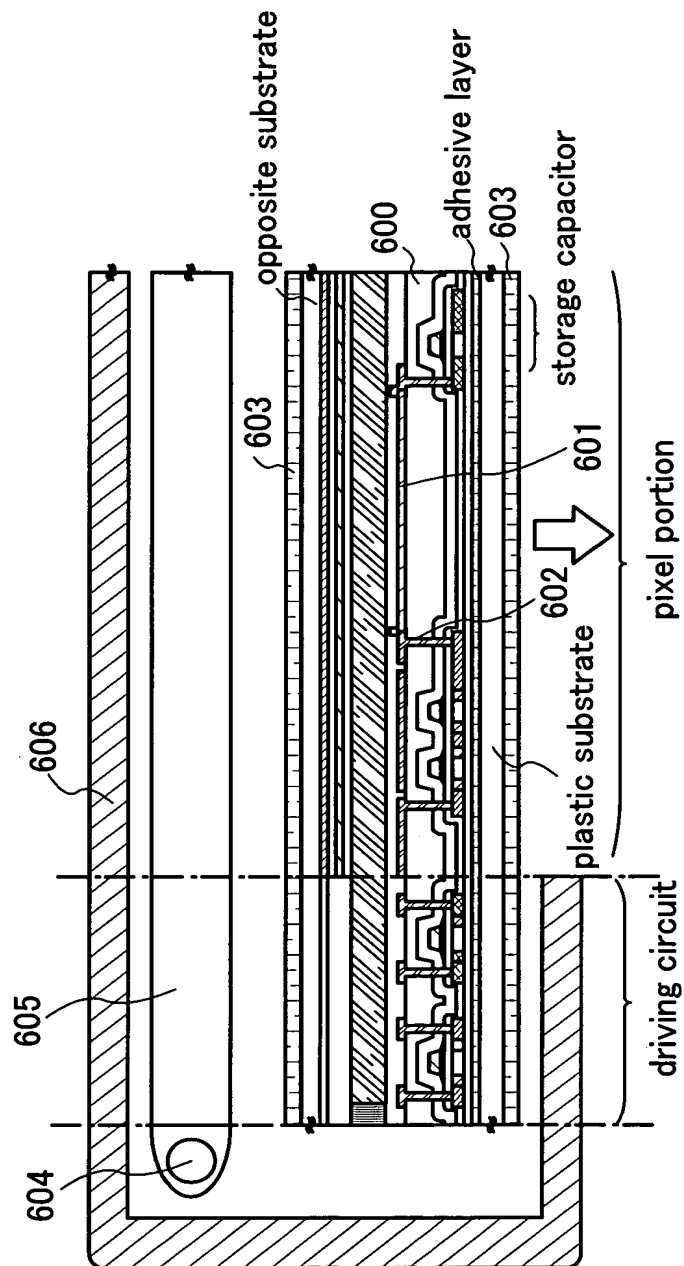




Fig.9

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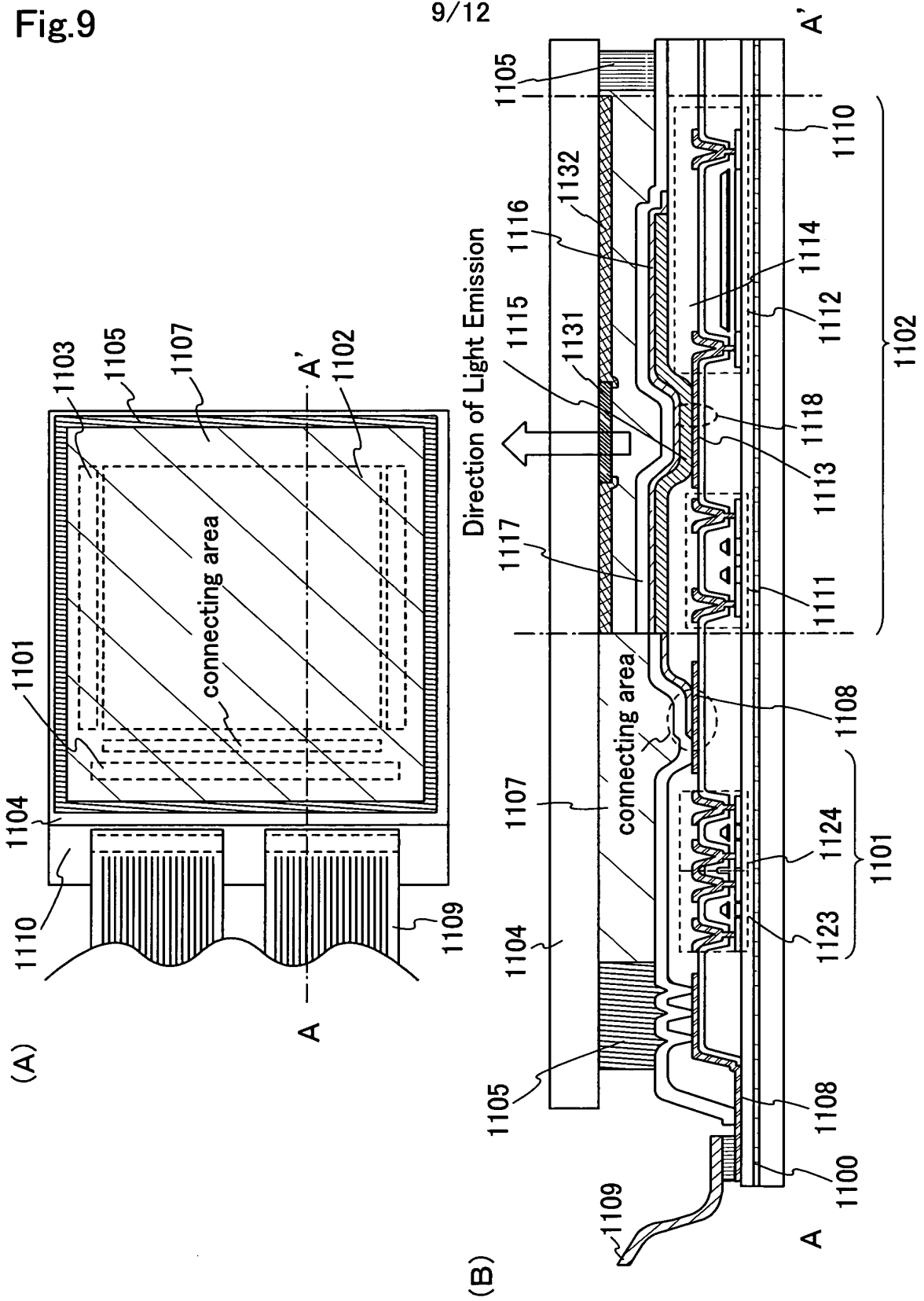


Fig.10

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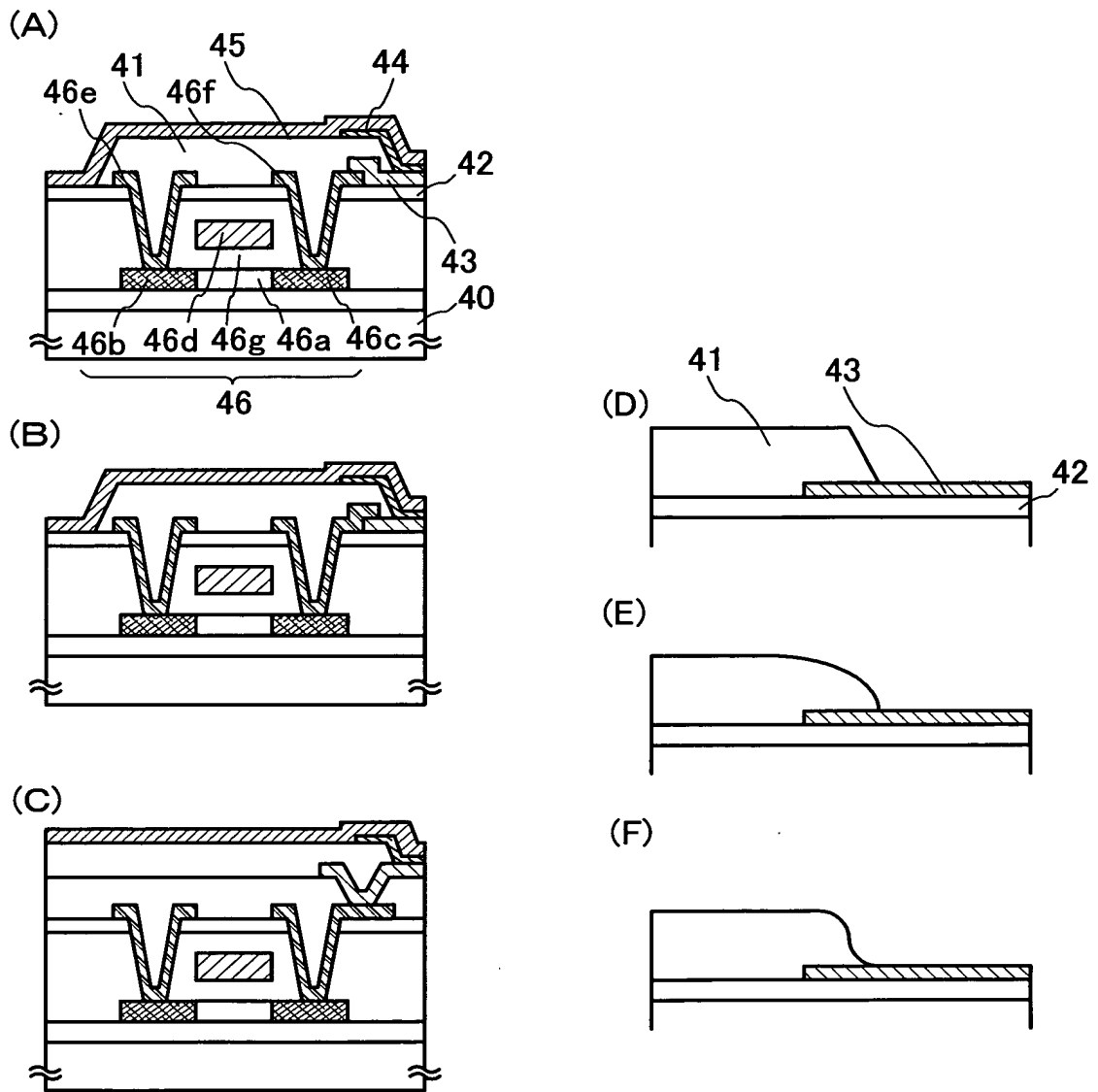


Fig.11

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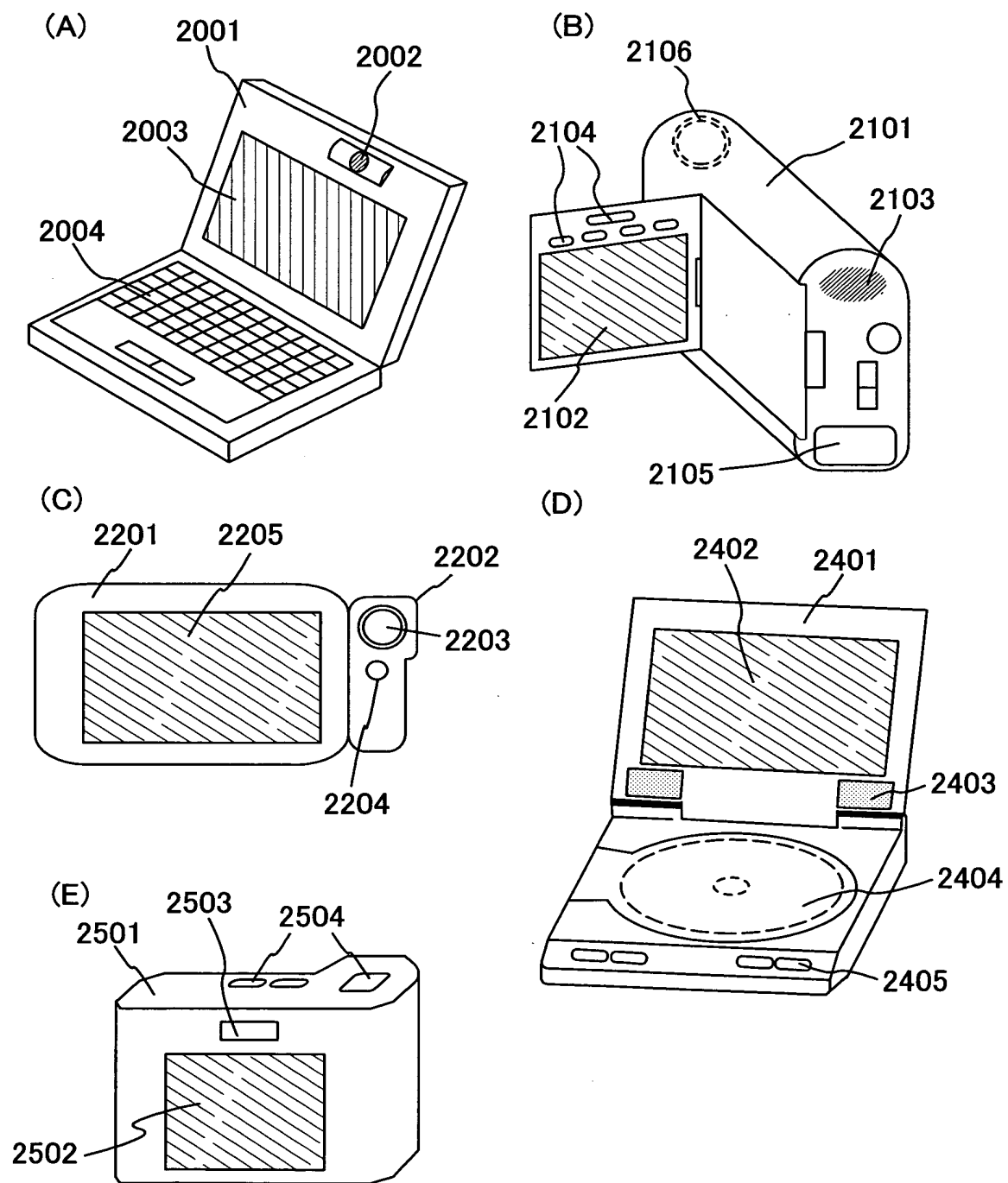
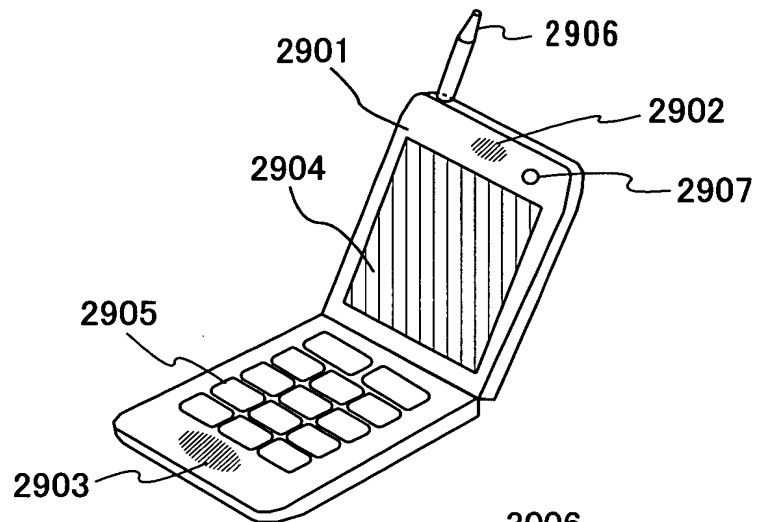


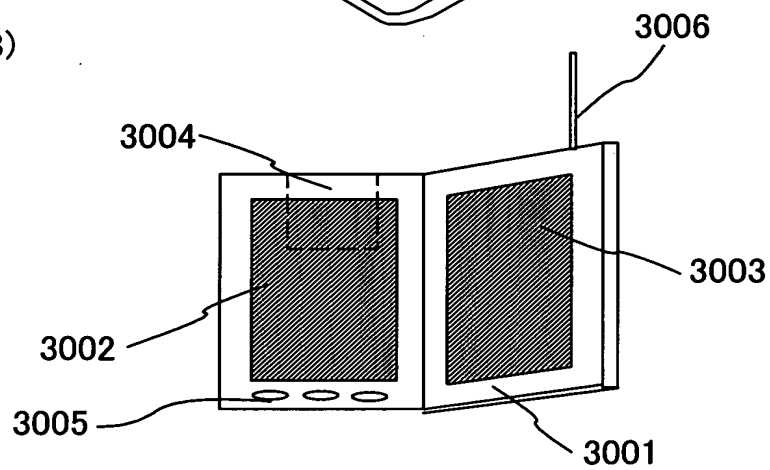
Fig.12

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(A)



(B)



(C)

